

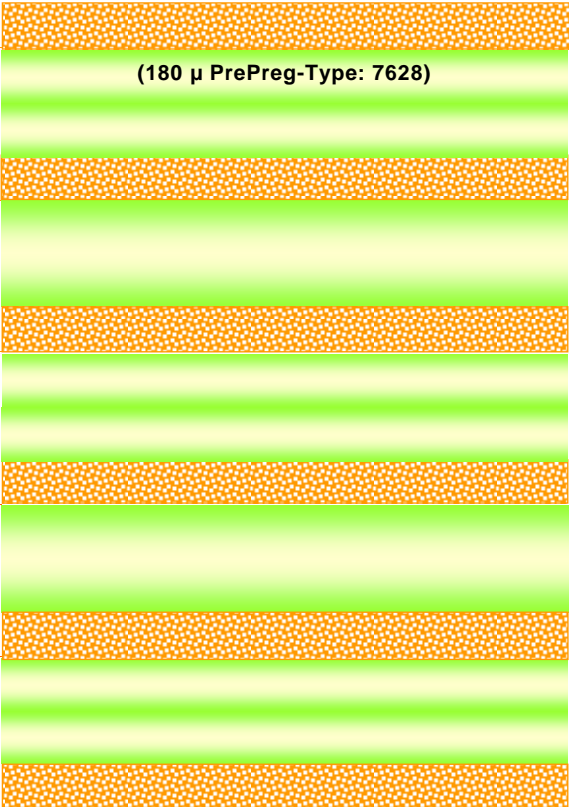
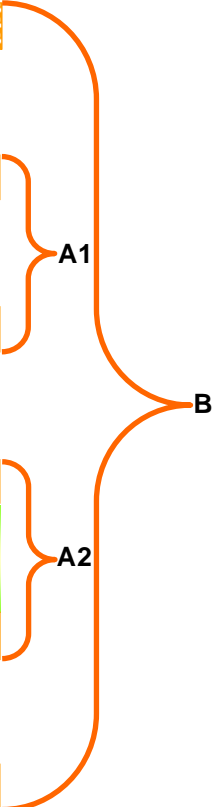
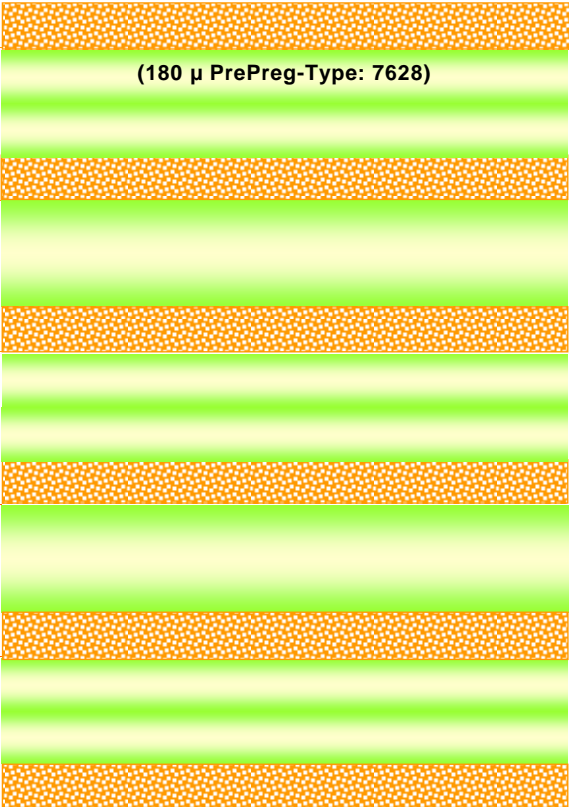
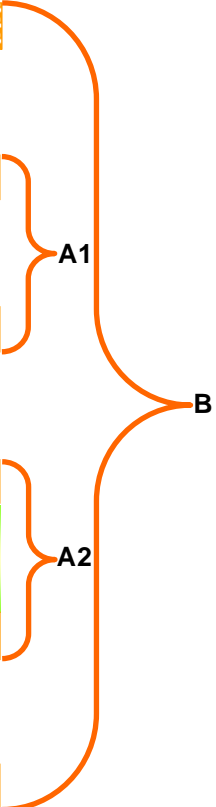
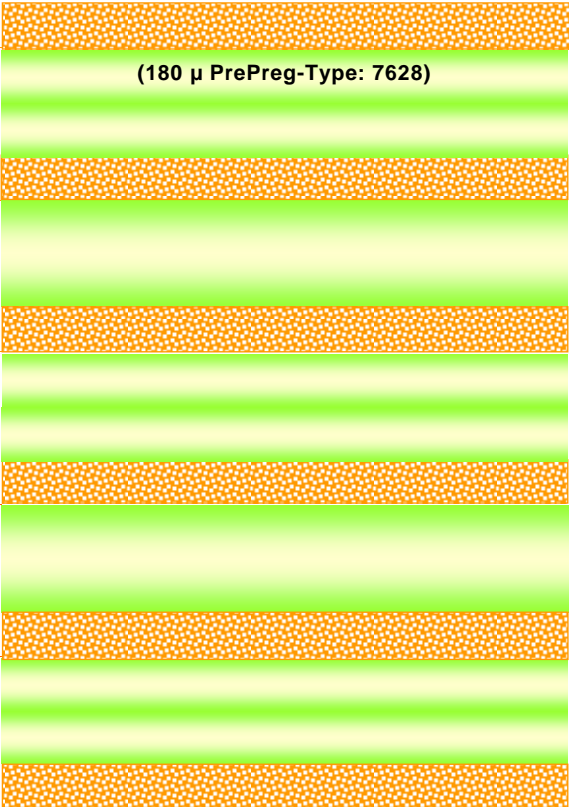
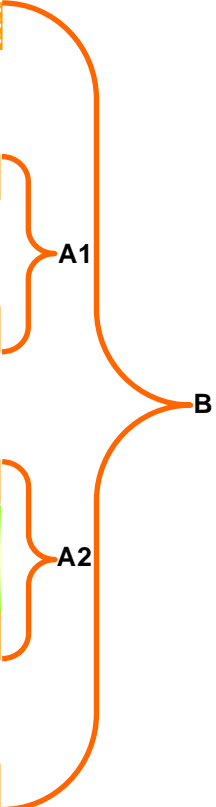
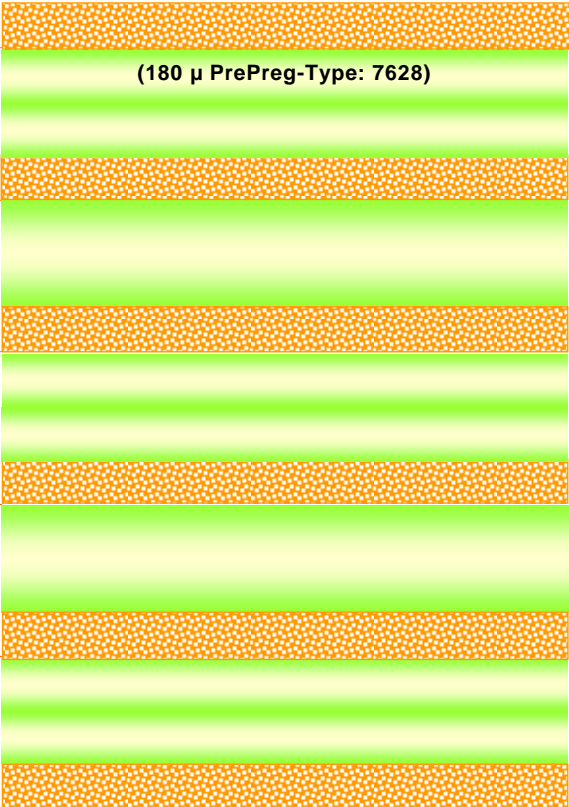
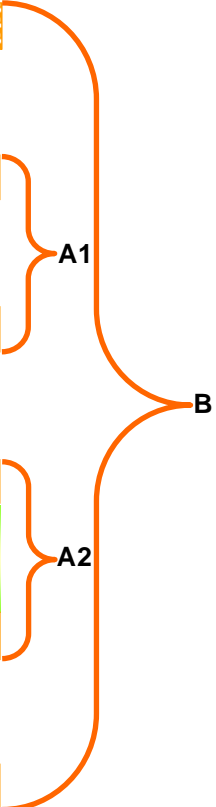
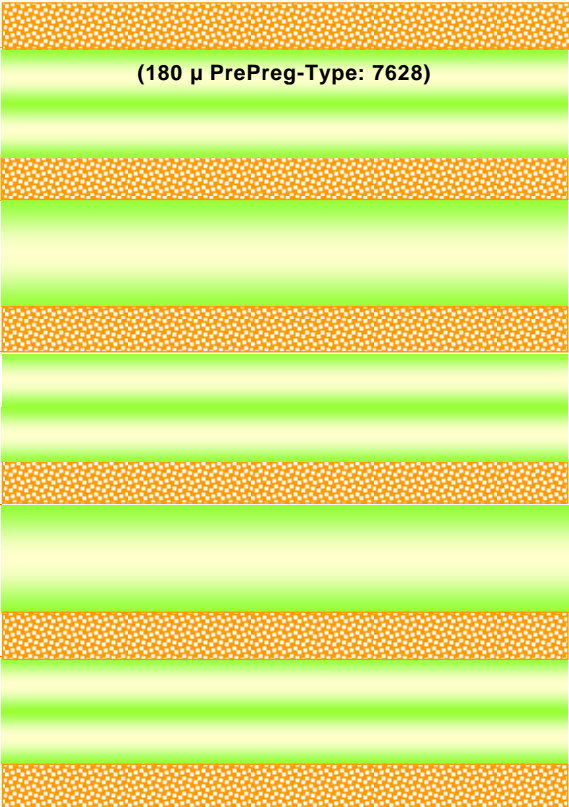
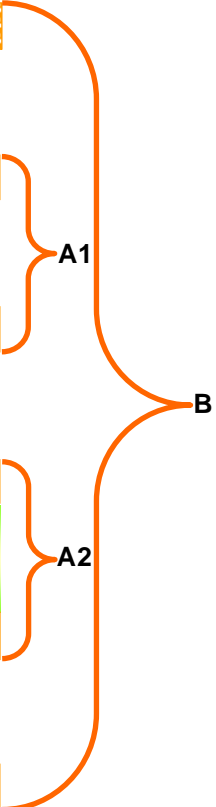
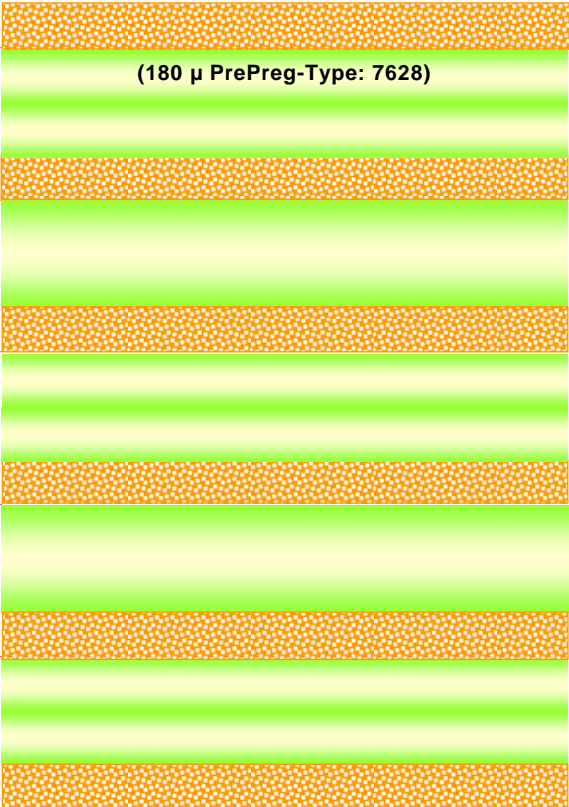
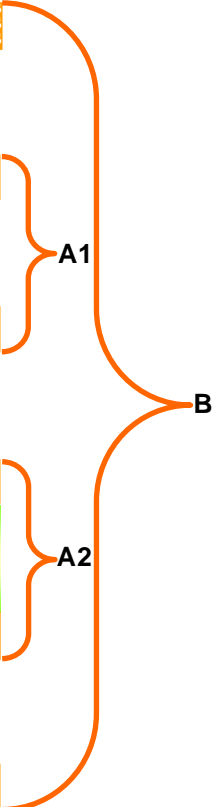
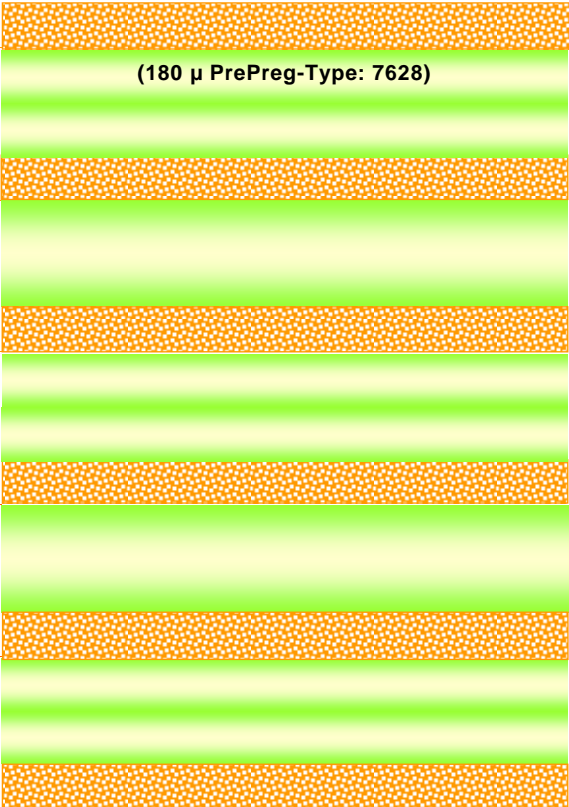
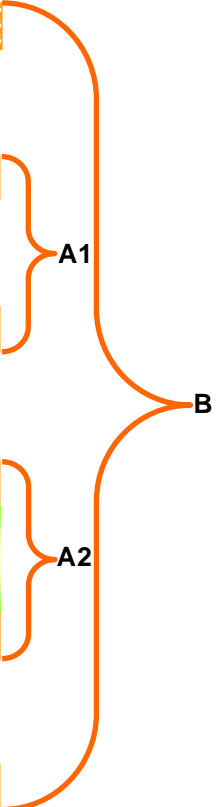
Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 230 FR4 60 L41.70 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_230_FR4_60_L41.70_p18

Layers	in μ	Material	Build-Up	Assembly								
Layer-1	60 μ	Copper										
	180 μ	Prepreg										
Layer-2	180 μ	Prepreg										
	70 μ	Copper										
Layer-3	410 μ	L-FR4										
	70 μ	Copper										
Layer-4	180 μ	Prepreg										
	180 μ	Prepreg										
Layer-5	70 μ	Copper										
	410 μ	L-FR4										
Layer-99	70 μ	Copper										
	180 μ	Prepreg										
Layer-99	180 μ	Prepreg										
	60 μ	Copper										

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